

Sensors and Materials

Special Issue on

Sensing and Data Analysis Technologies for Living Environment, Health Care, Production Management, and Engineering/Science Education Applications

With the rapid development of the Internet of Things (IoT), many IoT scenarios and applications are being proposed, and the number of sensors required for IoT scenarios and applications is rapidly increasing, resulting in rapid growth of the sensor chip market. Many new sensing and data analysis technologies, such as sensor fusion, multisensor, cloud-based computing, and big data analysis technologies, are being intensively researched and rapidly developed to meet the need for more accurate and smart sensing.

The topics of this special issue will focus on sensing and data analysis technologies for living environmental, health care, industrial production management, and engineering/science education applications. Prospective authors are invited to submit their new manuscripts in line with the scope of this special issue.

Potential topics include but are not limited to the following:

- Sensors for pollution
- Early warning systems in the environment
- Production management technology using online sensing information
- Big data analysis in sensing systems
- Data analysis/computing using smart sensors
- Mobile and wearable sensors
- Structural health monitoring
- Various sensor technologies and sensing systems
- Sensor fusion and sensorless applications
- Sensors and applications in the natural environment, including land, air, and water

Manuscript Due	Dec. 31, 2022
First Round of Reviews	Jan. 31, 2023
Publication Date	Apr. 30, 2023

Lead Guest Editor

Chien-Jung Huang, Professor

Department of Applied Physics, National University of Kaohsiung, Taiwan;

Email: chien@nuk.edu.tw

Guest Editors

Rey-Chue Hwang, Professor

Department of Electrical Engineering, I-Shou University, Taiwan;

Email: rchwang@isu.edu.tw

Ja-Hao Chen, Professor

Department of Communications Engineering, Feng Chia University, Taichung, Taiwan;

Email: chiahaoc@fcu.edu.tw

Ba-Son Nguyen, Professor

Research Center for Applied Sciences, Lac Hong University, Vietnam;

Email: bason@lhu.edu.vn

(Attention)

As stated in Instructions to Authors in the Guidelines, the author(s) will be obliged to pay the publication fee upon the acceptance of the manuscript for publication (for example, JPY 99360 for 10 pages in Sensors and Materials format). If the quality of the English of your manuscript does not satisfy the journal standards, the authors will bear the proofreading fee (JPY 10000–30000), which will be charged with the publication fee.

If you have any questions, please feel free to contact the editorial staff at the address below.

Editorial Department of Sensors and Materials

MYU K.K.

1-23-3-303 Sendagi, Bunkyo-ku, Tokyo 113-0022, Japan

Tel: +81-3-3827-8549, Fax: +81-3-3827-8547

E-mail: myukk@myu-inc.jp

